

A. Amendments to the Claims

**RECEIVED
CENTRAL FAX CENTER
MAY 02 2008**

Please amend the claims as follows:

1. (Canceled)
2. (Currently amended) A solid state keyboard formed by:
 - (a) depositing a layer of decorative material onto at least a portion of a substrate;
 - (b) depositing a first layer of conductive material ~~as a thin film~~ onto at least a portion of the structure resulting from step (a), said first layer of conductive material being arranged in the form of a first sensor sensing electrode ~~having a shape amenable to substantial coverage by a predetermined object~~;
 - (c) depositing a second layer of conductive material onto at least a portion of the structure resulting from step (b), at least a portion of said second layer of conductive material overlying and being electrically coupled to at least a portion of said first layer of conductive material, said second layer of conductive material being arranged in the form of a first bonding pad and a first electrical trace coupling said first sensing electrode to said ~~and a first bonding pad~~; and
 - (d) connecting a first electrical circuit component to said first bonding pad.
3. (Currently amended) The solid state keyboard of claim 2, said second layer of conductive material further being arranged in the form of a second sensor sensing electrode ~~having a shape amenable to substantial coverage by a predetermined object~~.

4. (Currently amended) The solid state keyboard of claim 2 further formed by depositing a first layer of dielectric material onto at least a portion of the structure resulting from step (c), said first layer of dielectric material overlying at least a portion of one or both of said first layer of conductive material and said second layer of conductive material, said first layer of dielectric material being arranged in a form that enables connecting said first electrical circuit component to said first bonding pad.

5. (Previously presented) The solid state keyboard of claim 2 wherein said decorative material comprises an organic material.

6. (Previously presented) The solid state keyboard of claim 5 wherein said organic material comprises an epoxy.

7. (Previously presented) The solid state keyboard of claim 5 wherein said organic material is ultraviolet curable.

8. (Previously presented) The solid state keyboard of claim 2 wherein said first layer of conductive material is substantially transparent.

9. (Previously presented) The solid state keyboard of claim 2 wherein said step of connecting comprises soldering.

10. (Previously presented) The solid state keyboard of claim 4, said second layer of conductive material further being arranged in the form of a second bonding pad and said keyboard further formed by depositing a third layer of conductive material onto at least a portion of said first layer of dielectric material.

11. (Previously presented) The solid state keyboard of claim 10, at least a portion of said third layer of conductive material being electrically coupled to said second bonding pad.

12. (Previously presented) The solid state keyboard of claim 11 further formed by depositing a second layer of dielectric material onto at least a portion of said third layer of conductive material.

13-22. (Canceled)

23. (Currently amended) A solid state keyboard comprising:
a substrate;
at least one layer of decorative material disposed on at least a portion of said substrate;
a thin layer film of a first conductive material disposed on at least a portion of said decorative material, said thin layer film of a first conductive material being arranged in the form of a first sensor sensing electrode having a shape amenable to substantial coverage by a predetermined object;

a layer of a second conductive material disposed on at least a portion of said thin ~~layer film~~ of a first conductive material, said layer of a second conductive material arranged in the form of a second sensor sensing electrode ~~having a shape amenable to substantial coverage by a predetermined object~~, an electrical trace, and a bonding pad, said electrical trace coupling said second sensor electrode to said bonding pad; and

an electrical circuit component connected to said bonding pad.

24. (Previously presented) The solid state keyboard of claim 23 wherein said decorative material comprises an organic material.

25. (Previously presented) The solid state keyboard of claim 24 wherein said organic material comprises an epoxy.

26. (Currently amended) The solid state keyboard of claim 23 wherein said thin layer film of a first conductive material is substantially transparent.

27. (Previously presented) The solid state keyboard of claim 23 wherein said electrical component is soldered to said bonding pad.

28. (Currently amended) The solid state keyboard of claim 23 further comprising a mask disposed on at least a portion of said thin layer film of a first conductive material and at least a portion of said layer of a second conductive material, said mask being arranged in a form that enables connecting said electrical circuit component to said bonding pad.

29. (Previously presented) The solid state keyboard of claim 2 wherein said substrate separates said layer of decorative material from said first and second layers of conductive material.

30. (Previously presented) The solid state keyboard of claim 2 wherein said substrate does not separate said layer of decorative material from said first and second layers of conductive material.

31-32. (Canceled)

33. (Currently amended) A method of making a solid state keyboard comprising the steps of:

(a) depositing a layer of decorative material onto at least a portion of a substrate, either directly or onto an intervening layer of decorative material;

(b) depositing a first layer of conductive material ~~as a thin film~~ onto at least a portion of the structure resulting from step (a), said first layer of conductive material being arranged in the form of a first sensor sensing electrode ~~having a shape amenable to substantial coverage by a predetermined object~~;

(c) depositing a second layer of conductive material onto at least a portion of the structure resulting from step (b), at least a portion of said second layer of conductive material overlying and being electrically coupled to at least a portion of said first layer of conductive material, said second layer of conductive material being arranged in the form of a first bonding

pad and a first electrical trace coupling said first sensor electrode to said and a first bonding pad;
and

(d) connecting a first electrical circuit component to said first bonding pad.

34. (Previously presented) The method of claim 33 wherein said at least a first layer of decorative material comprises an epoxy.

35. (Previously presented) The method of claim 34 wherein said step of connecting comprises soldering.

36-38. (Canceled)

39. (New) The solid-state keyboard of claim 2 wherein said first layer of conductive material is plated and/or deposited as a thin film.

40. (New) The solid-state keyboard of claim 39 wherein said first layer of conductive material is formed by patterning and etching.

41. (New) The solid-state keyboard of claim 2 wherein said first layer of conductive material is deposited by screen printing and/or microdeposition.

42. (New) The solid-state keyboard of claim 2 wherein said first layer of decorative material comprises an epoxy and said first layer of conductive material is deposited as a thin film onto at least a portion of said layer of decorative material.

43. (New) The solid-state keyboard of claim 2, said second layer of conductive material further arranged in the form of a second sensor electrode, a second bonding pad, and a second electrical trace coupling said second sensor electrode to second bonding pad.

44. (New) A solid state keyboard comprising:

- a substrate;
- a layer of decorative material disposed on at least a portion of said substrate;
- a first layer of conductive material disposed on at least a portion of said layer of decorative material, said first layer of conductive material being arranged in the form of a first sensor electrode;
- a second layer of conductive material disposed on at least a portion of said first layer of conductive material, said second layer of conductive material being arranged in the form of a first bonding pad and a first electrical trace coupling said first sensing electrode to said first bonding pad; and
- a first electrical circuit component connected to said first bonding pad.

45. (New) The solid-state keyboard of claim 44, said second layer of conductive material further arranged in the form of a second sensor electrode, a second bonding pad, and a second electrical trace coupling said second sensor electrode to second bonding pad.

46. (New) A solid state keyboard formed by:

- (a) depositing a layer of decorative material onto at least a portion of a substrate;
- (b) depositing a thin layer of a first conductive material onto at least a portion of said decorative material, said thin layer of a first conductive material being arranged in the form of a first sensor electrode;
- (c) depositing a layer of a second conductive material onto at least a portion of said thin layer of a first conductive material, said layer of a second conductive material arranged in the form of a second sensor electrode, an electrical trace, and a bonding pad, said electrical trace coupling said second sensor electrode to said bonding pad; and
an electrical circuit component connected to said bonding pad.